

## Low-Power Linear Active Thermistor™ ICs

### Features

- Tiny Analog Temperature Sensor
- Available Packages: SC70-5
- Wide Temperature Measurement Range:
  - -40°C to +125°C
- Accuracy: ±4°C (max.), 0°C to +70°C
- Optimized for Analog-to-Digital Converters (ADCs):
  - **MCP9700**: 10.0 mV/°C (typ.)
  - **MCP9701**: 19.5 mV/°C (typ.)
- Wide Operating Voltage Range:
  - **MCP9700**: V<sub>DD</sub> = 2.3V to 5.5V
  - **MCP9701**: V<sub>DD</sub> = 3.1V to 5.5V
- Low Operating Current: 6 µA (typ.)
- Optimized to Drive Large Capacitive Loads

### Typical Applications

- Hard Disk Drives and Other PC Peripherals
- Entertainment Systems
- Home Appliance
- Office Equipment
- Battery Packs and Portable Equipment
- General Purpose Temperature Monitoring

### Description

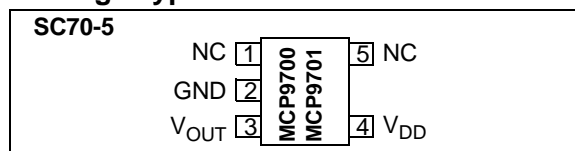
The MCP9700/01 Linear Active Thermistor™ Intergrated Circuit (IC) is an analog temperature sensor that converts temperature to analog voltage. It's a low-cost, low-power sensor with an accuracy of ±4°C from 0°C to +70°C while consuming 6 µA (typ.) of operating current.

Unlike resistive sensors (such as thermistors), the Linear Active Thermistor IC does not require an additional signal-conditioning circuit. Therefore, the biasing circuit development overhead for thermistor solutions can be avoided by implementing this low-cost device. The voltage output pin (V<sub>OUT</sub>) can be directly connected to the ADC input of a microcontroller. The MCP9700 and MCP9701 temperature coefficients are scaled to provide a 1 °C/bit resolution for an 8-bit ADC with a reference voltage of 2.5V and 5V, respectively.

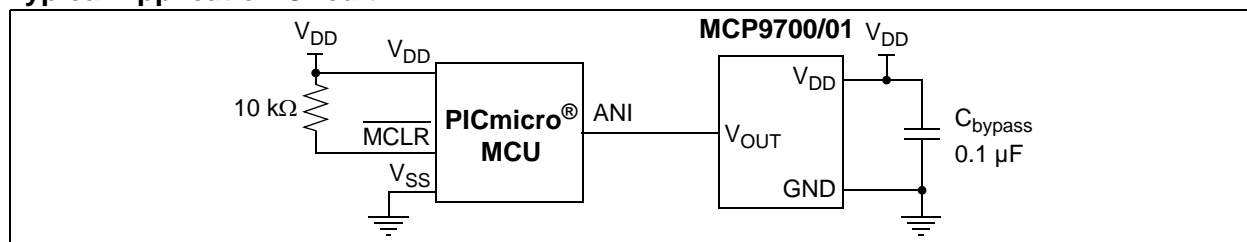
The MCP9700/01 provides a low-cost solution for applications that require measurement of a relative change of temperature. When measuring relative change in temperature from +25°C, an accuracy of ±1°C (typ.) can be realized from 0°C to +70°C. This accuracy can also be achieved by applying system calibration at +25°C.

In addition, this family is immune to the effects of parasitic capacitance and can drive large capacitive loads. This provides Printed Circuit Board (PCB) layout design flexibility by enabling the device to be remotely located from the microcontroller. Adding some capacitance at the output also helps the output transient response by reducing overshoots or undershoots. However, capacitive load is not required for sensor output stability.

### Package Type



### Typical Application Circuit



# MCP9700/01

## 1.0 ELECTRICAL CHARACTERISTICS

### Absolute Maximum Ratings †

$V_{DD}$ : ..... 6.0V  
 Storage temperature: ..... -65°C to +150°C  
 Ambient Temp. with Power Applied:.. -40°C to +125°C  
 Junction Temperature ( $T_J$ ):..... 150°C  
 ESD Protection On All Pins (HBM:MM):.... (4 kV:200V)  
 Latch-Up Current at Each Pin: ..... ±200 mA

†**Notice:** Stresses above those listed under “Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operational listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

### DC ELECTRICAL CHARACTERISTICS

Electrical Specifications: Unless otherwise indicated:						
MCP9700: $V_{DD}$ = 2.3V to 5.5V, GND = Ground, $T_A$ = -40°C to +125°C and No load.						
MCP9701: $V_{DD}$ = 3.1V to 5.5V, GND = Ground, $T_A$ = -10°C to +125°C and No load.						
Parameter	Sym	Min	Typ	Max	Unit	Conditions
<b>Power Supply</b>						
Operating Voltage Range	$V_{DD}$	2.3	—	5.5	V	MCP9700
	$V_{DD}$	3.1	—	5.5	V	MCP9701
Operating Current	$I_{DD}$	—	6	12	μA	
Power Supply Rejection Ratio	PSRR	—	0.1	—	°C/V	
<b>Sensor Accuracy (Notes 1, 2)</b>						
$T_A$ = +25°C	$T_{ACY}$	—	±1	—	°C	MCP9700 MCP9701
$T_A$ = 0°C to +70°C	$T_{ACY}$	-4.0	—	+4.0	°C	
$T_A$ = -40°C to +125°C	$T_{ACY}$	-4.0	—	+6.0	°C	
$T_A$ = -10°C to +125°C	$T_{ACY}$	-4.0	—	+6.0	°C	
<b>Sensor Output</b>						
Output Voltage:	$V_{0°C}$	—	500	—	mV	MCP9700
	$V_{0°C}$	—	400	—	mV	MCP9701
Temperature Coefficient	$T_{C1}$	—	10.0	—	mV/°C	MCP9700
	$T_{C1}$	—	19.5	—	mV/°C	MCP9701
Output Non-linearity	$V_{ONL}$	—	±0.5	—	°C	$T_A$ = 0°C to +70°C (Note 2)
Output Current	$I_{OUT}$	—	—	100	μA	
Output Impedance	$Z_{OUT}$	—	20	—	Ω	$I_{OUT}$ = 100 μA, f = 500 Hz
Output Load Regulation	$\Delta V_{OUT}/\Delta I_{OUT}$	—	1	—	Ω	$T_A$ = 0°C to +70°C, $I_{OUT}$ = 100 μA
Turn-on Time	$t_{ON}$	—	800	—	μs	
Typical Load Capacitance (Note 3)	$C_{LOAD}$	—	—	1000	pF	
Thermal Response to 63%	$t_{RES}$	—	1.3	—	s	30°C (Air) to +125°C (Fluid Bath) (Note 4)

- Note 1:** The MCP9700 accuracy is tested with  $V_{DD}$  = 3.3V, while the MCP9701 accuracy is tested with  $V_{DD}$  = 5.0V.  
**Note 2:** The MCP9700/01 is characterized using the first-order or linear equation, as shown in Equation 4-2.  
**Note 3:** The MCP9700/01 family is characterized and production-tested with a capacitive load of 1000 pF.  
**Note 4:** Thermal response with 1x1 inch, dual-sided copper clad.

## TEMPERATURE CHARACTERISTICS

**Electrical Specifications:** Unless otherwise indicated:

**MCP9700:**  $V_{DD} = 2.3V$  to  $5.5V$ , GND = Ground,  $T_A = -40^{\circ}C$  to  $+125^{\circ}C$  and No load.

**MCP9701:**  $V_{DD} = 3.1V$  to  $5.5V$ , GND = Ground,  $T_A = -10^{\circ}C$  to  $+125^{\circ}C$  and No load.

Parameters	Sym	Min	Typ	Max	Units	Conditions
<b>Temperature Ranges</b>						
Specified Temperature Range	$T_A$	-40	—	+125	$^{\circ}C$	<b>MCP9700 (Note)</b>
	$T_A$	-10	—	+125	$^{\circ}C$	<b>MCP9701 (Note)</b>
Operating Temperature Range	$T_A$	-40	—	+125	$^{\circ}C$	
Storage Temperature Range	$T_A$	-65	—	+150	$^{\circ}C$	
<b>Thermal Package Resistances</b>						
Thermal Resistance, 5L-SC70	$\theta_{JA}$	—	331	—	$^{\circ}C/W$	

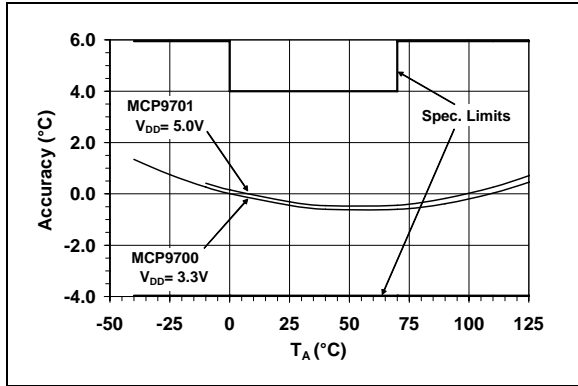
**Note:** Operation in this range must not cause  $T_J$  to exceed Maximum Junction Temperature ( $+150^{\circ}C$ ).

# MCP9700/01

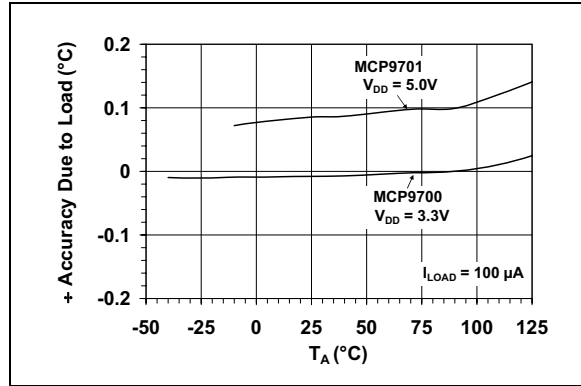
## 2.0 TYPICAL PERFORMANCE CURVES

**Note:** The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore outside the warranted range.

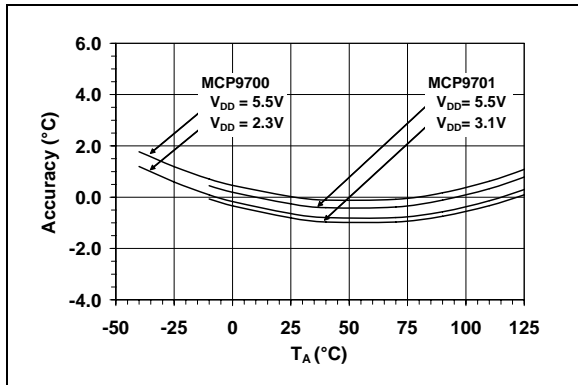
**Note:** Unless otherwise indicated, **MCP9700:**  $V_{DD} = 2.3V$  to  $5.5V$ ; **MCP9701:**  $V_{DD} = 3.1V$  to  $5.5V$ ; GND = Ground,  $C_{bypass} = 0.1 \mu F$ .



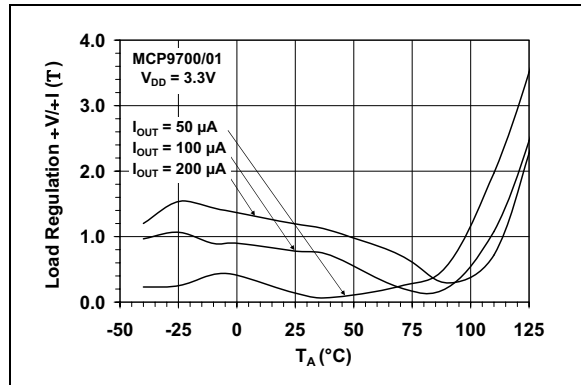
**FIGURE 2-1:** Accuracy vs. Ambient Temperature.



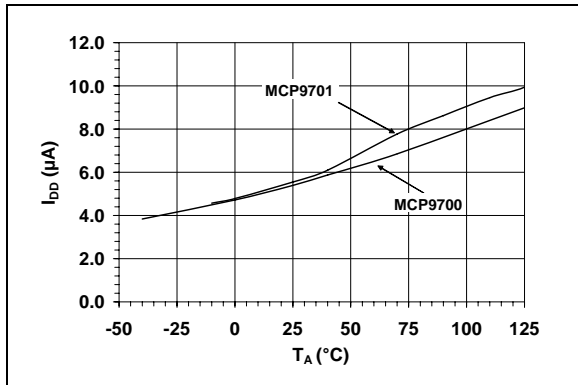
**FIGURE 2-4:** Changes in Accuracy vs. Ambient Temperature (Due to Load).



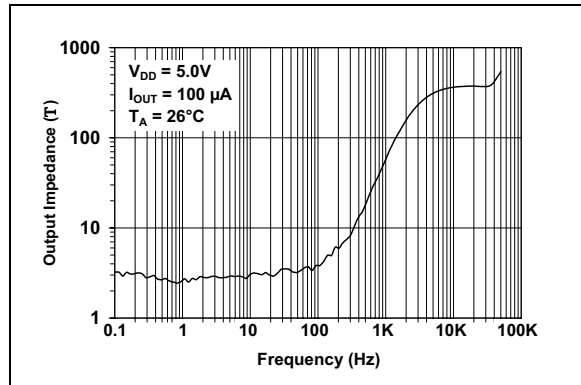
**FIGURE 2-2:** Accuracy vs. Ambient Temperature, with  $V_{DD}$ .



**FIGURE 2-5:** Load Regulation vs. Ambient Temperature.

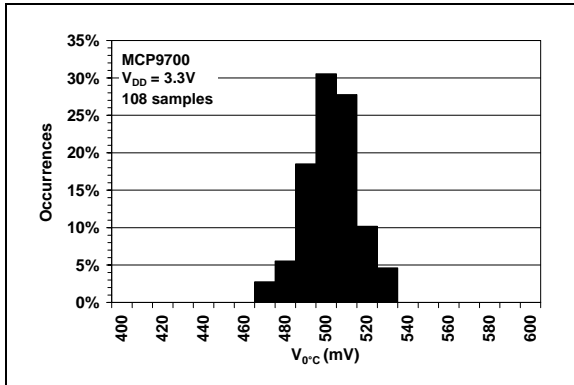


**FIGURE 2-3:** Supply Current vs. Temperature.

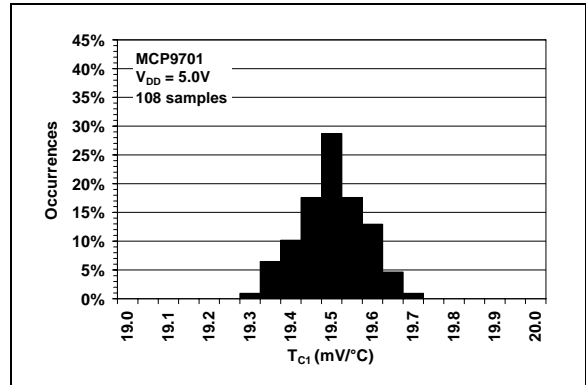


**FIGURE 2-6:** Output Impedance vs. Frequency.

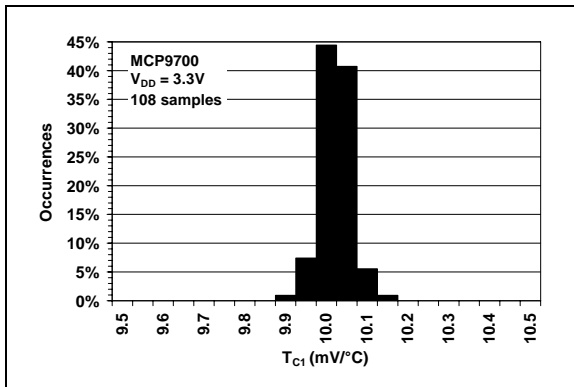
**Note:** Unless otherwise indicated, **MCP9700:**  $V_{DD} = 2.3V$  to  $5.5V$ ; **MCP9701:**  $V_{DD} = 3.1V$  to  $5.5V$ ; GND = Ground,  $C_{bypass} = 0.1 \mu F$ .



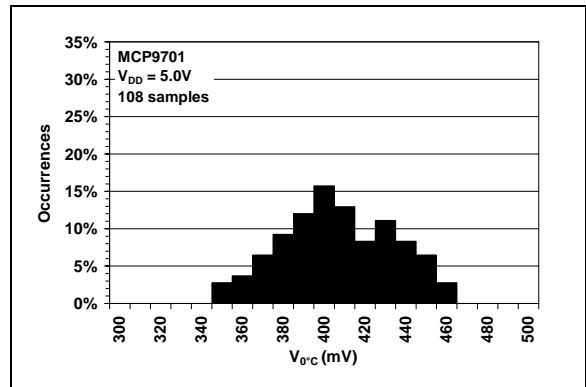
**FIGURE 2-7:** Output Voltage at  $0^{\circ}C$  (MCP9700).



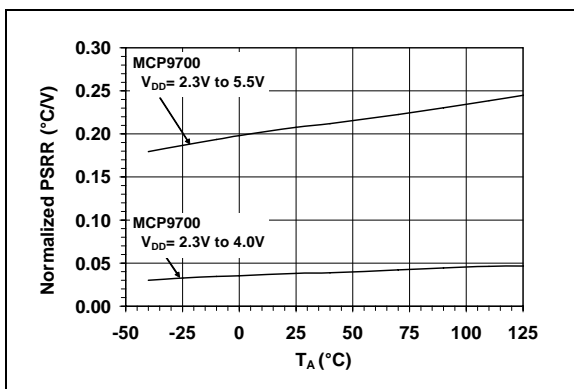
**FIGURE 2-10:** Output Voltage at  $0^{\circ}C$  (MCP9701).



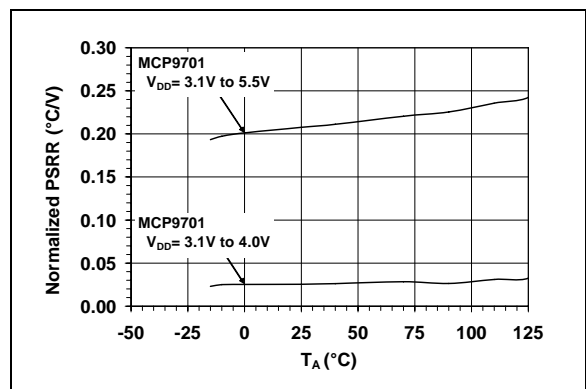
**FIGURE 2-8:** Occurrences vs. Temperature Coefficient (MCP9700).



**FIGURE 2-11:** Occurrences vs. Temperature Coefficient (MCP9701).



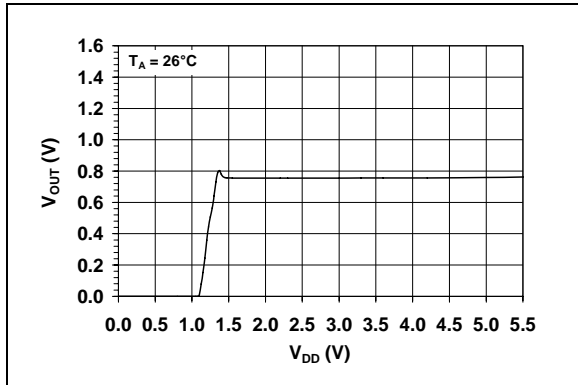
**FIGURE 2-9:** Power Supply Rejection Ratio (PSRR) vs. Ambient Temperature.



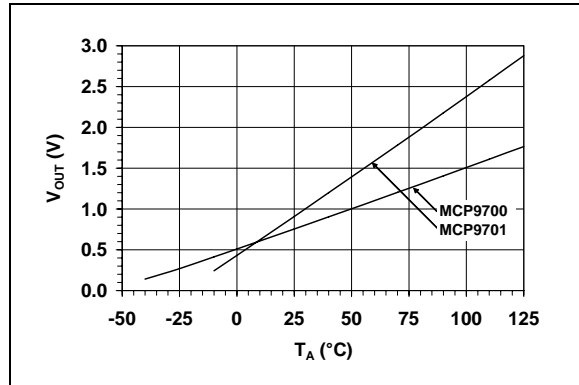
**FIGURE 2-12:** Power Supply Rejection Ratio (PSRR) vs. Temperature.

# MCP9700/01

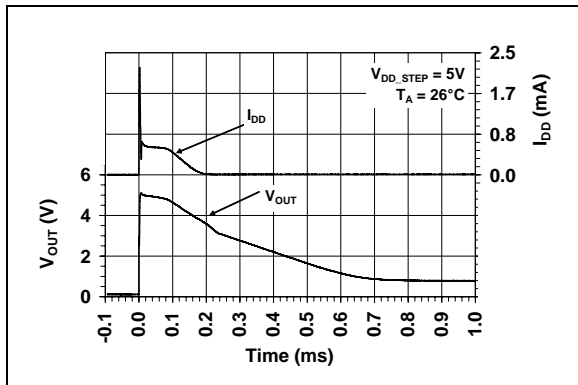
**Note:** Unless otherwise indicated, **MCP9700:**  $V_{DD} = 2.3V$  to  $5.5V$ ; **MCP9701:**  $V_{DD} = 3.1V$  to  $5.5V$ ; GND = Ground,  $C_{bypass} = 0.1 \mu F$ .



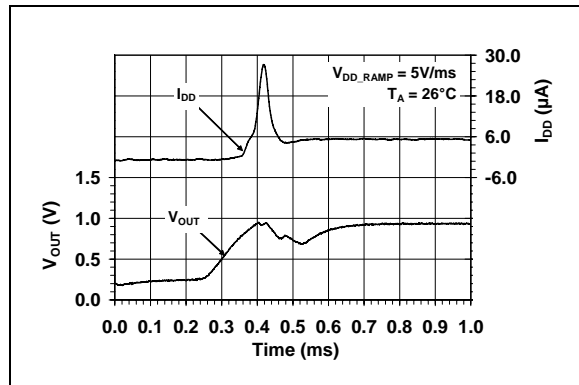
**FIGURE 2-13:** Output Voltage vs. Power Supply.



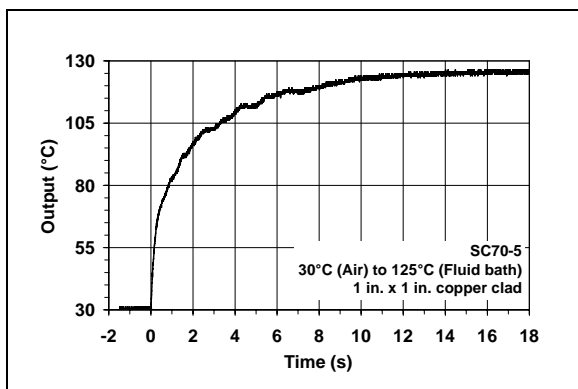
**FIGURE 2-16:** Output Voltage vs. Ambient Temperature.



**FIGURE 2-14:** Output vs. Settling Time to step  $V_{DD}$ .



**FIGURE 2-17:** Output vs. Settling Time to Ramp  $V_{DD}$ .



**FIGURE 2-15:** Thermal Response.

## 3.0 PIN DESCRIPTIONS

The descriptions of the pins are listed in DC Electrical Characteristics.

**TABLE 3-1: PIN FUNCTION TABLE**

Pin No.	Name	Function
1	NC	No Connect
2	GND	Power Ground Pin
3	V <sub>OUT</sub>	Output Voltage Pin
4	V <sub>DD</sub>	Power Supply Input
5	NC	No Connect

### 3.1 Power Ground Pin (GND)

GND is the system ground pin.

### 3.2 Output Voltage Pin (V<sub>OUT</sub>)

The sensor output can be measured at V<sub>OUT</sub>. The voltage range over the operating temperature range for the MCP9700 is 100 mV to 1.75V and for the MCP9701, 200 mV to 3V .

### 3.3 Power Supply Input (V<sub>DD</sub>)

The operating voltage as specified in the DC Electrical Characteristics table is applied to V<sub>DD</sub>.

# MCP9700/01

## 4.0 APPLICATIONS INFORMATION

The Linear Active Thermistor™ IC uses an internal diode to measure temperature. The diode electrical characteristics have a temperature coefficient that provides a change in voltage based on the relative ambient temperature from -40°C to 125°C. The change in voltage is scaled to a temperature coefficient of 10.0 mV/°C (typ.) for the MCP9700 and 19.5 mV/°C (typ.) for the MCP9701. The output voltage at 0°C is also scaled to 500 mV (typ.) and 400 mV (typ.) for the MCP9700 and MCP9701, respectively. This linear scale is described in the first-order transfer function shown in Equation 4-1.

### EQUATION 4-1: SENSOR TRANSFER FUNCTION

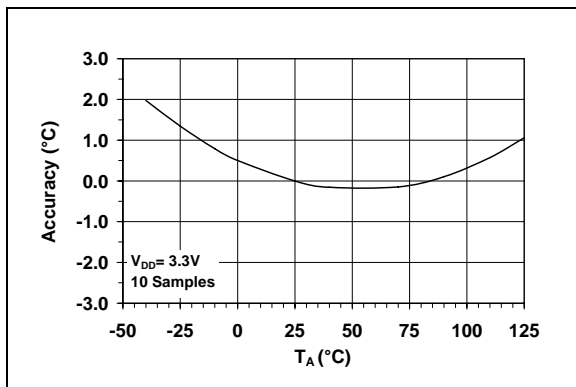
$$V_{OUT} = T_{C1} \cdot T_A + V_{0^\circ C}$$

Where:

- $T_A$  = Ambient Temperature
- $V_{OUT}$  = Sensor Output Voltage
- $V_{0^\circ C}$  = Sensor Output Voltage at 0°C
- $T_{C1}$  = Temperature Coefficient

### 4.1 Improving Accuracy

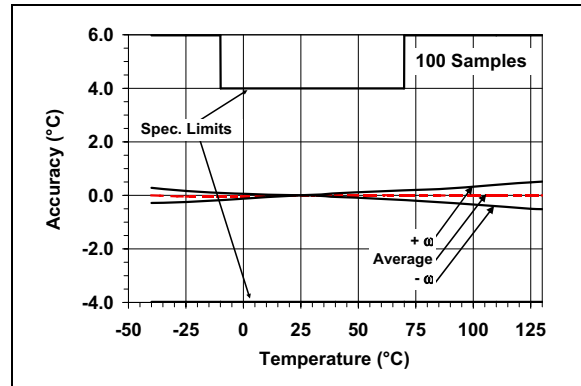
The MCP9700/01 accuracy can be improved by performing a system calibration at a specific temperature. For example, calibrating the system at +25°C ambient improves the measurement accuracy to a ±0.5°C (typ.) from 0°C to +70°C, as shown in Figure 4-1. Therefore, when measuring relative temperature change, this family measures temperature with higher accuracy.



**FIGURE 4-1:** Relative Accuracy to +25°C vs. Temperature.

The change in accuracy from the calibration temperature is due to the output non-linearity from the first-order equation, as specified in Equation 4-2. The accuracy can be further improved by compensating for the output non-linearity.

For higher accuracy using a sensor compensation technique, refer to AN1001 “IC Temperature Sensor Accuracy Compensation with a PICmicro® Microcontroller” (DS01001). The application note shows that if the MCP9700 is compensated in addition to room temperature calibration, the sensor accuracy can be improved to ±0.5°C (typ.) accuracy over the operating temperature (Figure 4-2).



**FIGURE 4-2:** MCP9700 Calibrated Sensor Accuracy.

The compensation technique provides a linear temperature reading. A firmware look-up table can be generated to compensate for the sensor error.

### 4.2 Shutdown Using Microcontroller I/O Pin

The MCP9700/01 low operating current of 6 μA (typ.) makes it ideal for battery-powered applications. However, for applications that require tighter current budget, this device can be powered using a microcontroller Input/Output (I/O) pin. The I/O pin can be toggled to shut down the device. In such applications, the microcontroller internal digital switching noise is emitted to the MCP9700/01 as power supply noise. This switching noise compromises measurement accuracy. Therefore, a decoupling capacitor and series resistor will be necessary to filter out the system noise.

### 4.3 Layout Considerations

The MCP9700/01 does not require any additional components to operate. However, it is recommended that a decoupling capacitor of 0.1 μF to 1 μF be used between the V<sub>DD</sub> and GND pins. In high-noise applications, connect the power supply voltage to the V<sub>DD</sub> pin using a 200Ω resistor with a 1 μF decoupling capacitor. A high-frequency ceramic capacitor is recommended. It is necessary for the capacitor to be located as close as possible to the V<sub>DD</sub> and GND pins in order to provide effective noise protection. In addition, avoid tracing digital lines in close proximity to the sensor.



## 4.4 Thermal Considerations

The MCP9700/01 measures temperature by monitoring the voltage of a diode located in the die. A low-impedance thermal path between the die and the PCB is provided by the pins. Therefore, the MCP9700/01 effectively monitors the temperature of the PCB. However, the thermal path for the ambient air is not as efficient because the plastic device package functions as a thermal insulator from the die. This limitation applies to plastic-packaged silicon temperature sensors. If the application requires measuring ambient air, the PCB needs to be designed with proper thermal conduction to the sensor pins.

The MCP9700/01 is designed to source/sink 100  $\mu\text{A}$  (max.). The power dissipation due to the output current is relatively insignificant. The effect of the output current can be described using Equation 5-1.

### EQUATION 4-2: EFFECT OF SELF-HEATING

$$T_J - T_A = \theta_{JA}(V_{DD}I_{DD} + (V_{DD} - V_{OUT})I_{OUT})$$

Where:

- $T_J$  = Junction Temperature
- $T_A$  = Ambient Temperature
- $\theta_{JA}$  = Package Thermal Resistance  
(331°C/W)
- $V_{OUT}$  = Sensor Output Voltage
- $I_{OUT}$  = Sensor Output Current
- $I_{DD}$  = Operating Current
- $V_{DD}$  = Operating Voltage

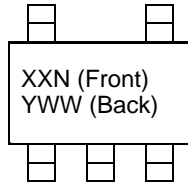
At  $T_A = +25^\circ\text{C}$  ( $V_{OUT} = 0.75\text{V}$ ) and maximum specification of  $I_{DD} = 12 \mu\text{A}$ ,  $V_{DD} = 5.5\text{V}$  and  $I_{OUT} = +100 \mu\text{A}$ , the self-heating due to power dissipation ( $T_J - T_A$ ) is  $0.179^\circ\text{C}$ .

# MCP9700/01

## 5.0 PACKAGING INFORMATION

### 5.1 Package Marking Information

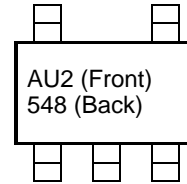
5-Lead SC-70 (MCP9700)



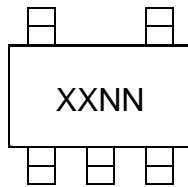
Device	Code
MCP9700	AUN
MCP9701	AVN

**Note:** Applies to 5-Lead SC-70.

Example:



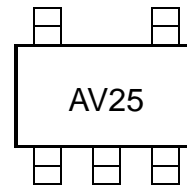
5-Lead SC-70 (MCP9701)



Device	Code
MCP9700	AUNN
MCP9701	AVNN

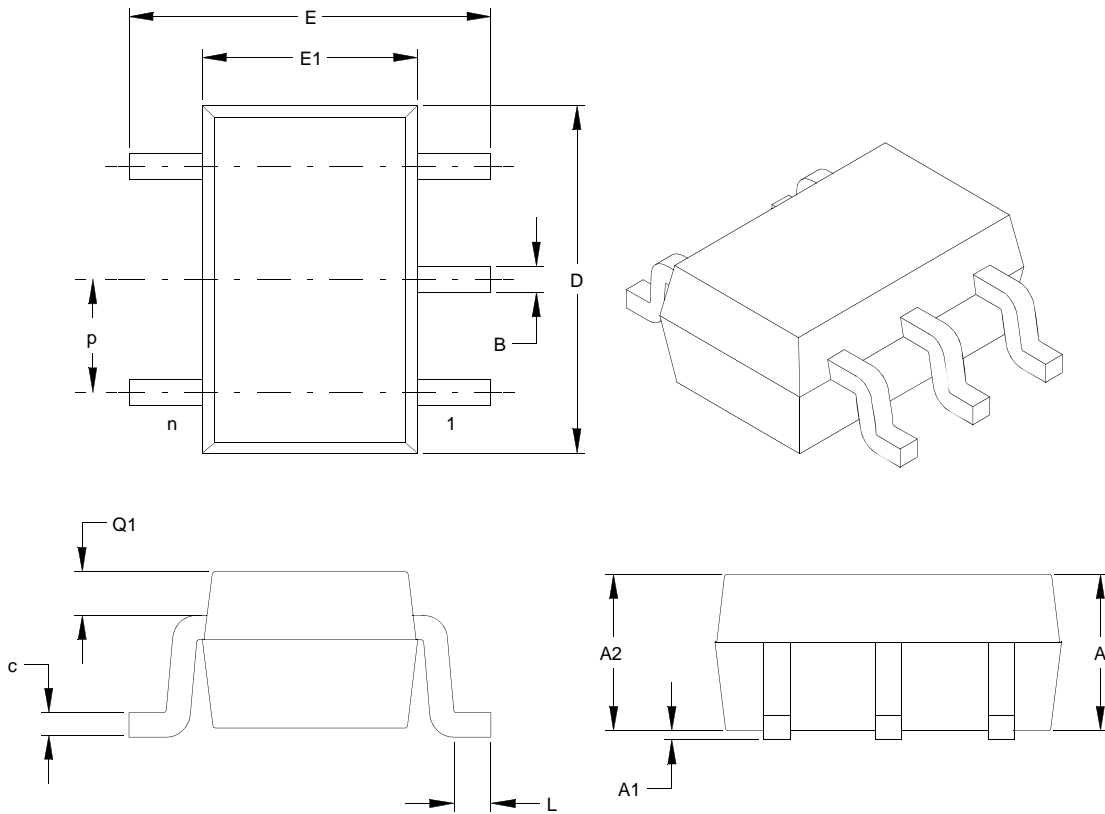
**Note:** Applies to 5-Lead SC-70.

Example:



<b>Legend:</b>	XX...X	Customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week '01')
	NNN	Alphanumeric traceability code
	(e3)	Pb-free JEDEC designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator (e3) can be found on the outer packaging for this package.
<b>Note:</b>	In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.	

## 5-Lead Plastic Small Outline Transistor (LT) (SC-70)



Units		INCHES			MILLIMETERS*		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n	5			5		
Pitch	P	.026 (BSC)			0.65 (BSC)		
Overall Height	A	.031		.043	0.80		1.10
Molded Package Thickness	A2	.031		.039	0.80		1.00
Standoff	A1	.000		.004	0.00		0.10
Overall Width	E	.071		.094	1.80		2.40
Molded Package Width	E1	.045		.053	1.15		1.35
Overall Length	D	.071		.087	1.80		2.20
Foot Length	L	.004		.012	0.10		0.30
Top of Molded Pkg to Lead Shoulder	Q1	.004		.016	0.10		0.40
Lead Thickness	c	.004		.007	0.10		0.18
Lead Width	B	.006		.012	0.15		0.30

\* Controlling Parameter

**Notes:**

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .005" (0.127mm) per side.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

See ASME Y14.5M

JEITA (EIAJ) Standard: SC-70

Drawing No. C04-061

Revised 07-19-05

# MCP9700/01

---

NOTES:

## APPENDIX A: REVISION HISTORY

### Revision B (October 2005)

The following is the list of modifications:

- Added **Section 3.0 “Pin Descriptions”**
- Added the Linear Active Thermistor™ IC trademark
- Removed the 2<sup>nd</sup> order temperature equation and the temperature coefficient histogram
- Added a reference to AN1001 and corresponding verbiage
- Added Figure 4-2 and corresponding verbiage

### Revision A (March 2005)

- Original Release of this Document.

# MCP9700/01

---

NOTES:

## PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

<u>PART NO.</u>	-	X	XX
Device		Temperature Range	Package
Device:		MCP9700T: Linear Active Thermistor™ IC, Tape and Reel, Pb free MCP9701T: Linear Active Thermistor™ IC, Tape and Reel, Pb free	
Temperature Range:	E	= -40°C to +125°C	
Package:	LT	= Plastic Small Outline Transistor, 5-lead	

**Examples:**

- a) MCP9700T-E/LT: Linear Active Thermistor™ IC, Tape and Reel, -40°C to +125°C, 5LD SC70 package.
- a) MCP9701T-E/LT: Linear Active Thermistor™ IC, Tape and Reel, -40°C to +125°C, 5LD SC70 package.

# MCP9700/01

---

NOTES:



---

**Note the following details of the code protection feature on Microchip devices:**

- Microchip products meet the specification contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is one of the most secure families of its kind on the market today, when used in the intended manner and under normal conditions.
- There are dishonest and possibly illegal methods used to breach the code protection feature. All of these methods, to our knowledge, require using the Microchip products in a manner outside the operating specifications contained in Microchip's Data Sheets. Most likely, the person doing so is engaged in theft of intellectual property.
- Microchip is willing to work with the customer who is concerned about the integrity of their code.
- Neither Microchip nor any other semiconductor manufacturer can guarantee the security of their code. Code protection does not mean that we are guaranteeing the product as "unbreakable."

Code protection is constantly evolving. We at Microchip are committed to continuously improving the code protection features of our products. Attempts to break Microchip's code protection feature may be a violation of the Digital Millennium Copyright Act. If such acts allow unauthorized access to your software or other copyrighted work, you may have a right to sue for relief under that Act.

---

Information contained in this publication regarding device applications and the like is provided only for your convenience and may be superseded by updates. It is your responsibility to ensure that your application meets with your specifications. MICROCHIP MAKES NO REPRESENTATIONS OR WARRANTIES OF ANY KIND WHETHER EXPRESS OR IMPLIED, WRITTEN OR ORAL, STATUTORY OR OTHERWISE, RELATED TO THE INFORMATION, INCLUDING BUT NOT LIMITED TO ITS CONDITION, QUALITY, PERFORMANCE, MERCHANTABILITY OR FITNESS FOR PURPOSE. Microchip disclaims all liability arising from this information and its use. Use of Microchip's products as critical components in life support systems is not authorized except with express written approval by Microchip. No licenses are conveyed, implicitly or otherwise, under any Microchip intellectual property rights.

**Trademarks**

The Microchip name and logo, the Microchip logo, Accuron, dsPIC, KEELOQ, microID, MPLAB, PIC, PICmicro, PICSTART, PRO MATE, PowerSmart, rPIC, and SmartShunt are registered trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.


AmpLab, FilterLab, Migratable Memory, MXDEV, MXLAB, PICMASTER, SEEVAL, SmartSensor and The Embedded Control Solutions Company are registered trademarks of Microchip Technology Incorporated in the U.S.A.

Analog-for-the-Digital Age, Application Maestro, dsPICDEM, dsPICDEM.net, dsPICworks, ECAN, ECONOMONITOR, FanSense, FlexROM, fuzzyLAB, In-Circuit Serial Programming, ICSP, ICEPIC, Linear Active Thermistor, MPASM, MPLIB, MPLINK, MPSIM, PCKIT, PICDEM, PICDEM.net, PICLAB, PICtail, PowerCal, PowerInfo, PowerMate, PowerTool, rLAB, rPICDEM, Select Mode, Smart Serial, SmartTel, Total Endurance and WiperLock are trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.

SQTP is a service mark of Microchip Technology Incorporated in the U.S.A.

All other trademarks mentioned herein are property of their respective companies.

© 2005, Microchip Technology Incorporated, Printed in the U.S.A., All Rights Reserved.

 Printed on recycled paper.

**QUALITY MANAGEMENT SYSTEM  
CERTIFIED BY DNV  
== ISO/TS 16949:2002 ==**

*Microchip received ISO/TS-16949:2002 quality system certification for its worldwide headquarters, design and wafer fabrication facilities in Chandler and Tempe, Arizona and Mountain View, California in October 2003. The Company's quality system processes and procedures are for its PICmicro® 8-bit MCUs, KEELOQ® code hopping devices, Serial EEPROMs, microperipherals, nonvolatile memory and analog products. In addition, Microchip's quality system for the design and manufacture of development systems is ISO 9001:2000 certified.*



---

## WORLDWIDE SALES AND SERVICE

---

### AMERICAS

#### Corporate Office

2355 West Chandler Blvd.  
Chandler, AZ 85224-6199  
Tel: 480-792-7200  
Fax: 480-792-7277  
Technical Support:  
<http://support.microchip.com>  
Web Address:  
[www.microchip.com](http://www.microchip.com)

#### Atlanta

Alpharetta, GA  
Tel: 770-640-0034  
Fax: 770-640-0307

#### Boston

Westborough, MA  
Tel: 774-760-0087  
Fax: 774-760-0088

#### Chicago

Itasca, IL  
Tel: 630-285-0071  
Fax: 630-285-0075

#### Dallas

Addison, TX  
Tel: 972-818-7423  
Fax: 972-818-2924

#### Detroit

Farmington Hills, MI  
Tel: 248-538-2250  
Fax: 248-538-2260

#### Kokomo

Kokomo, IN  
Tel: 765-864-8360  
Fax: 765-864-8387

#### Los Angeles

Mission Viejo, CA  
Tel: 949-462-9523  
Fax: 949-462-9608

#### San Jose

Mountain View, CA  
Tel: 650-215-1444  
Fax: 650-961-0286

#### Toronto

Mississauga, Ontario,  
Canada  
Tel: 905-673-0699  
Fax: 905-673-6509

### ASIA/PACIFIC

#### Australia - Sydney

Tel: 61-2-9868-6733  
Fax: 61-2-9868-6755

#### China - Beijing

Tel: 86-10-8528-2100  
Fax: 86-10-8528-2104

#### China - Chengdu

Tel: 86-28-8676-6200  
Fax: 86-28-8676-6599

#### China - Fuzhou

Tel: 86-591-8750-3506  
Fax: 86-591-8750-3521

#### China - Hong Kong SAR

Tel: 852-2401-1200  
Fax: 852-2401-3431

#### China - Qingdao

Tel: 86-532-8502-7355  
Fax: 86-532-8502-7205

#### China - Shanghai

Tel: 86-21-5407-5533  
Fax: 86-21-5407-5066

#### China - Shenyang

Tel: 86-24-2334-2829  
Fax: 86-24-2334-2393

#### China - Shenzhen

Tel: 86-755-8203-2660  
Fax: 86-755-8203-1760

#### China - Shunde

Tel: 86-757-2839-5507  
Fax: 86-757-2839-5571

#### China - Wuhan

Tel: 86-27-5980-5300  
Fax: 86-27-5980-5118

#### China - Xian

Tel: 86-29-8833-7250  
Fax: 86-29-8833-7256

### ASIA/PACIFIC

#### India - Bangalore

Tel: 91-80-2229-0061  
Fax: 91-80-2229-0062

#### India - New Delhi

Tel: 91-11-5160-8631  
Fax: 91-11-5160-8632

#### India - Pune

Tel: 91-20-2566-1512  
Fax: 91-20-2566-1513

#### Japan - Yokohama

Tel: 81-45-471-6166  
Fax: 81-45-471-6122

#### Korea - Gumi

Tel: 82-54-473-4301  
Fax: 82-54-473-4302

#### Korea - Seoul

Tel: 82-2-554-7200  
Fax: 82-2-558-5932 or  
82-2-558-5934

#### Malaysia - Penang

Tel: 604-646-8870  
Fax: 604-646-5086

#### Philippines - Manila

Tel: 632-634-9065  
Fax: 632-634-9069

#### Singapore

Tel: 65-6334-8870  
Fax: 65-6334-8850

#### Taiwan - Hsin Chu

Tel: 886-3-572-9526  
Fax: 886-3-572-6459

#### Taiwan - Kaohsiung

Tel: 886-7-536-4818  
Fax: 886-7-536-4803

#### Taiwan - Taipei

Tel: 886-2-2500-6610  
Fax: 886-2-2508-0102

#### Thailand - Bangkok

Tel: 66-2-694-1351  
Fax: 66-2-694-1350

### EUROPE

#### Austria - Weis

Tel: 43-7242-2244-399  
Fax: 43-7242-2244-393

#### Denmark - Copenhagen

Tel: 45-4450-2828  
Fax: 45-4485-2829

#### France - Paris

Tel: 33-1-69-53-63-20  
Fax: 33-1-69-30-90-79

#### Germany - Munich

Tel: 49-89-627-144-0  
Fax: 49-89-627-144-44

#### Italy - Milan

Tel: 39-0331-742611  
Fax: 39-0331-466781

#### Netherlands - Drunen

Tel: 31-416-690399  
Fax: 31-416-690340

#### Spain - Madrid

Tel: 34-91-352-30-52  
Fax: 34-91-352-11-47

#### UK - Wokingham

Tel: 44-118-921-5869  
Fax: 44-118-921-5820



08/24/05